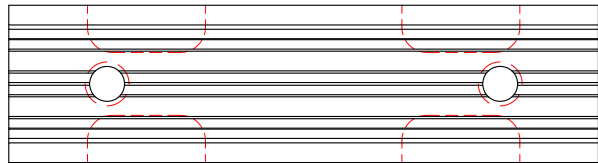


4

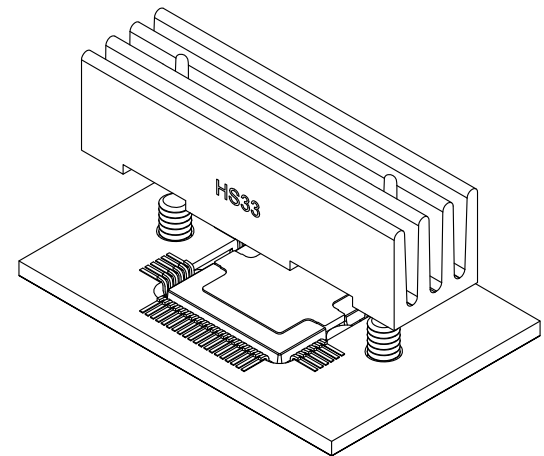
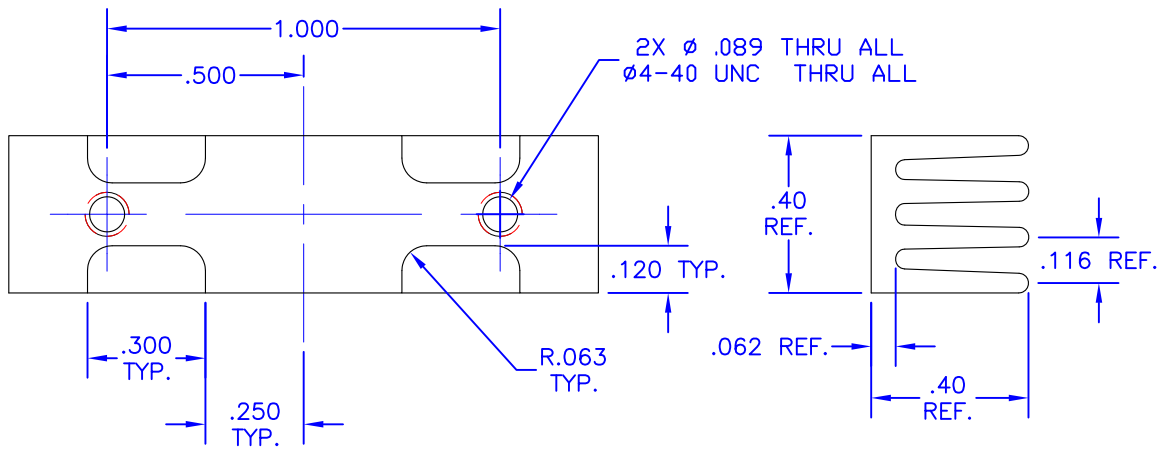
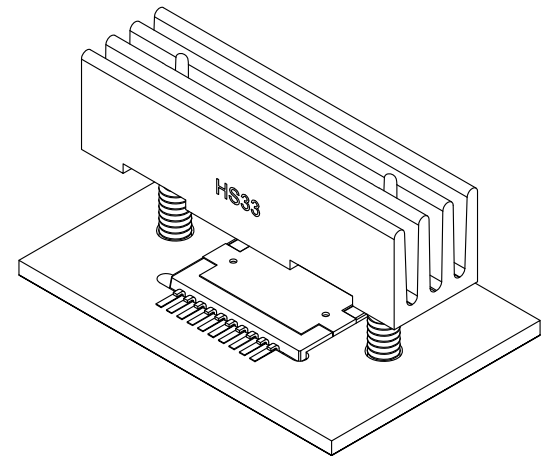
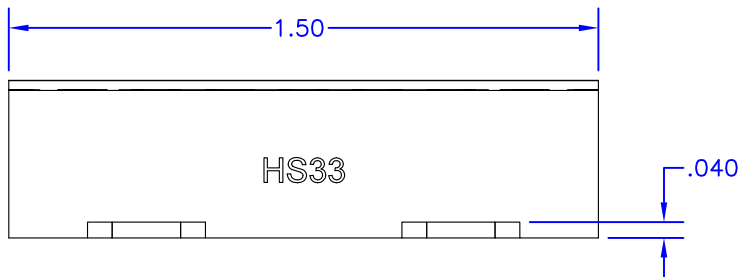
3

2

1



INVERTED THROUGH CIRCUIT BOARD  
MOUNTING WITH HEAT SINK  
(Patent Pending)



**NOTES:**

1. Unless otherwise noted, all dimensions are in inches.
2. Break all sharp edges, de-burr & remove loose chips.
3. Material: 6063-T5 aluminum alloy. Make from Aavid extrusion 70920
4. Mark with contrasting ink as shown, if specified by P.O.
5. Approximate Weight: 0.22 oz [6.3g]

TOLERANCES - UNLESS OTHERWISE SPECIFIED
.XX = ±.05 [.002]
.XXX = ±.005 [.0002]
ANG. = ±2°



TITLE: <b>DK &amp; HQ PACKAGE HEATSINK</b>	MODEL:
SUBJECT: <b>MECHANICAL DRAWING</b>	
ENGINEER: <b>D-M</b>	DRAWN BY: <b>P.ECK</b>
DCA: <b>12436</b>	SHL: <b>1</b> OF <b>1</b>

FILENAME: <b>HS33</b>	REV: <b>B</b>	DATE: <b>14NOV12</b>
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4

3

2

1

D

D

C

C

B

B

A

A